

# RSD046P05

## Pch 45V 4.5A Power MOSFET

$V_{DSS}$	-45V
R <sub>DS(on)</sub> (Max.)	155m $\Omega$
I <sub>D</sub>	−4.5A
$P_D$	15W

#### Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

# Application

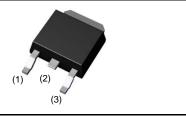
**Switching Power Supply** 

Automotive Motor Drive

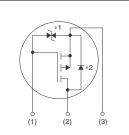
Automotive Solenoid Drive

#### Outline

CPT3 (SC-63) <SOT-428>



## •Inner circuit



- (1) Gate
- (2) Drain
- (3) Source
- \*1 ESD PROTECTION DIODE
- \*2 BODY DIODE

Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	046P05

## • Absolute maximum ratings $(T_a = 25^{\circ}C)$

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	<b>–45</b>	V
Continuous drain surrent	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±4.5	А
Continuous drain current	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	±2.4	А
Pulsed drain current		I <sub>D,pulse</sub> *2	±9.0	А
Gate - Source voltage		$V_{GSS}$	±20	V
Avalanche energy, single pulse		E <sub>AS</sub> *3	14.3	mJ
Avalanche current		I <sub>AR</sub> *3	-4.5	А
$T_c = 25$ °C		P <sub>D</sub>	15	W
Power dissipation $T_a = 25$ °C		P <sub>D</sub>	0.85	W
Junction temperature		T <sub>j</sub>	150	°C
Range of storage temperature		T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Parameter	Symbol	Values			Unit
raiailletei	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - ambient	$R_{thJC}$	-	-	8.33	°C/W

# ●Electrical characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Conditions Min.		Values		
Parameter	Symbol	Conditions			Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = -1mA$	-45	ı	ı	V	
		$V_{DS} = -45V, V_{GS} = 0V$			1		
Zoro goto voltago droin gurrant		T <sub>j</sub> = 25°C	-	-	<b>–1</b>	μА	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = -45V, V_{GS} = 0V$			-100		
		T <sub>j</sub> = 125°C	-	-			
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μΑ	
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = -10V, I_{D} = -1mA$	-1	-	-3	V	
		$V_{GS} = -10V, I_D = -4.5A$	ı	110	155		
		$V_{GS} = -4.5V, I_D = -4.5A$	-	160	225		
Static drain - source on - state resistance	$R_{DS(on)}^{}^{*4}}$	$V_{GS} = -4.0V, I_D = -4.5A$	-	185	260	mΩ	
		$V_{GS} = -10V, I_D = -4.5A$		180	250		
		T <sub>j</sub> = 125°C	-		250		
Forward transfer admittance	g <sub>fs</sub>	$V_{DS} = -10V, I_D = -4.5A$	3	6	-	S	

# ●Electrical characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
r ai ai ii e lei	Symbol Conditions —		Min.	Тур.	Max.	Offic	
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	550	1		
Output capacitance	C <sub>oss</sub>	$V_{DS} = -10V$	-	100	1	pF	
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	50	1		
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq -25V$ , $V_{GS} = -10V$	-	8	1		
Rise time	t <sub>r</sub> *4	$I_D = -2.0A$	-	8	-	nc	
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L = 12\Omega$	-	35	-	ns	
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	8	-		

# •Gate Charge characteristics( $T_a = 25$ °C)

Parameter	Cymbol	Conditions		Values		Unit
Parameter	Symbol Conditions –		Min.	Тур.	Max.	
Total gate charge	$Q_g^{*4}$	$V_{DD} \simeq -25V$	-	12	-	
Gate - Source charge	Q <sub>gs</sub> *4	$I_D = -4.5A$	-	2.2	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	$V_{GS} = -5V$	-	2.2	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq -30V$ , $I_D = -4.5A$	-	-3.4	-	V

# ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Values	Unit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Offic
Continuous source current	I <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	6	-4.5	Α
Pulsed source current	I <sub>SM</sub> *2	1 c = 25 C	-	-	-9	Α
Forward voltage	V <sub>SD</sub> *4	$V_{GS} = 0V, I_{S} = -4.5A$	-	-	-1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = -4.5A	-	40	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = -100A/μs	-	60	-	μС

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $^{\simeq}$  1mH,  $V_{DD}$  = -25V, Rg =  $10\Omega$ , starting  $T_j$  =  $25^{\circ}C$ 

<sup>\*4</sup> Pulsed

Fig.1 Power Dissipation Derating Curve

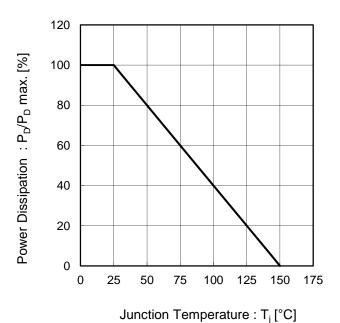
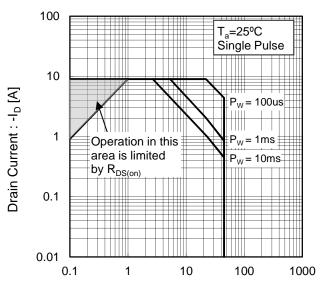
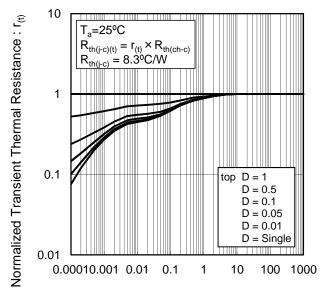


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width :  $P_W[s]$ 

Fig.4 Avalanche Current vs Inductive Load

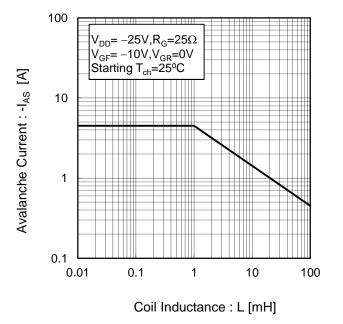
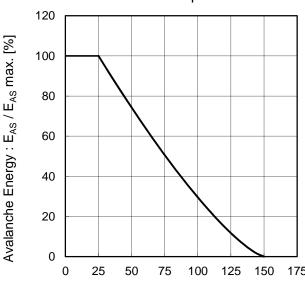
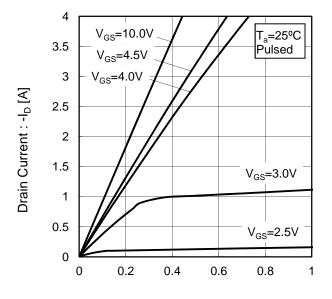


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



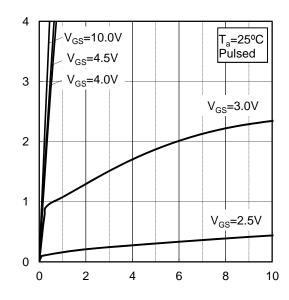
Junction Temperature : T<sub>i</sub> [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : -V<sub>DS</sub> [V]

Drain Current: -I<sub>D</sub> [A]

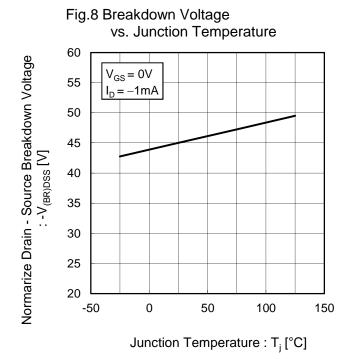
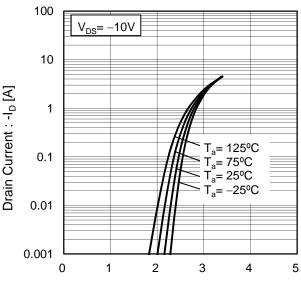


Fig.9 Typical Transfer Characteristics



Gate - Source Voltage : -V<sub>GS</sub> [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature

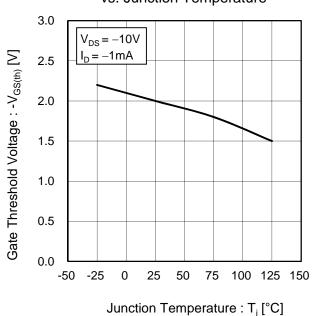
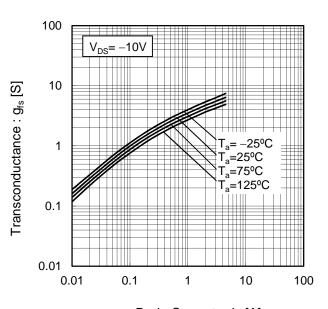


Fig.11 Transconductance vs. Drain Current



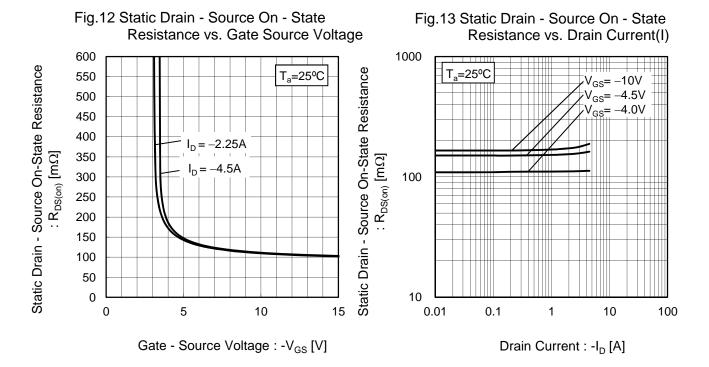
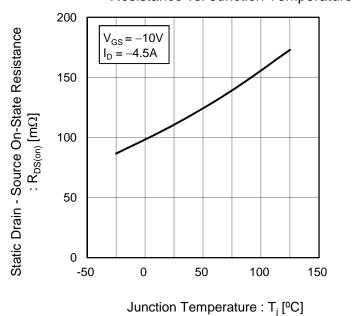


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Resistance vs. Drain Current(II)

1000  $V_{GS} = -10V$   $T_a = 125^{\circ}C$   $T_a = 75^{\circ}C$   $T_a = -25^{\circ}C$   $T_a = -25^{\circ}C$   $T_a = -25^{\circ}C$   $T_a = -25^{\circ}C$   $T_a = -25^{\circ}C$ 

Drain Current : -I<sub>D</sub> [A]

Fig.15 Static Drain - Source On - State

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

1000

V<sub>GS</sub>= -4.5V

T<sub>a</sub>=125°C

T<sub>a</sub>=75°C

T<sub>a</sub>=25°C

T<sub>a</sub>=-25°C

T<sub>a</sub>=-25°C

T<sub>a</sub>=-25°C

T<sub>a</sub>=-100

Drain Current: -I<sub>D</sub> [A]

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV) 1000 T<sub>a</sub>=125°C Static Drain - Source On-State Resistance -4.0V \_a=75°C Ta=25ºC –25°C  $: R_{\mathsf{DS}(\mathsf{on})} \ [\mathsf{m}\Omega]$ 100 10 0.01 0.1 1 10 100 Drain Current: -I<sub>D</sub> [A]

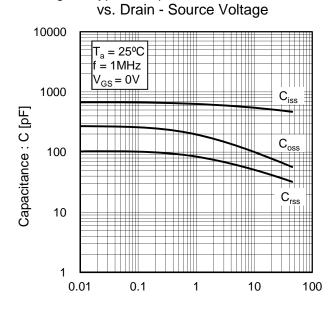
120 100 Drain Current Dissipation : I<sub>D</sub>/I<sub>D</sub> max. (%) 80 60 40 20 0 0 25 50 75 100 125 150 175

Fig.18 Drain Current Derating Curve



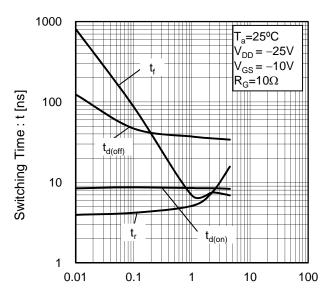
Junction Temperature : T<sub>i</sub> [°C]

Fig.19 Typical Capacitance



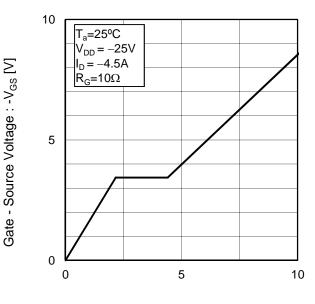
Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.20 Switching Characteristics



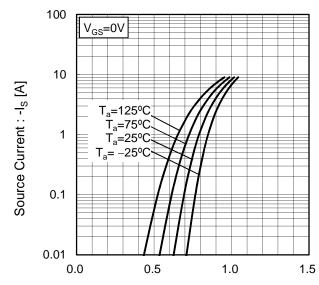
Drain Current : -I<sub>D</sub> [A]

Fig.21 Dynamic Input Characteristics

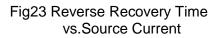


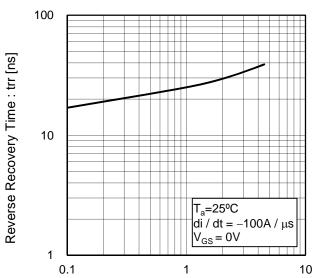
Total Gate Charge :  $Q_g$  [nC]

Fig.22 Source Current vs. Source - Drain Voltage



Source-Drain Voltage : -V<sub>SD</sub> [V]





Source Current : -I<sub>S</sub> [A]

## ●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

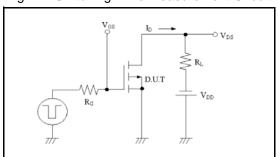


Fig.2-1 Gate Charge Measurement Circuit

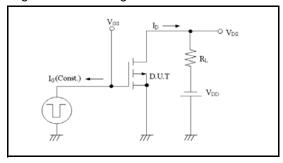


Fig.3-1 Avalanche Measurement Circuit

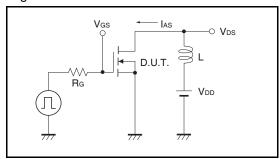


Fig.1-2 Switching Waveforms

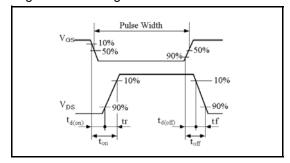


Fig.2-2 Gate Charge Waveform

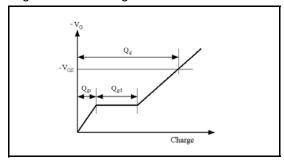
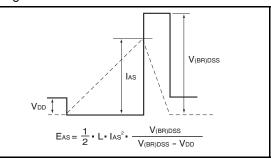
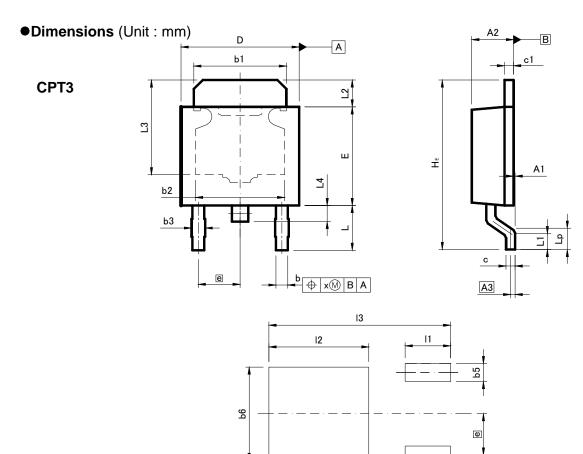


Fig.3-2 Avalanche Waveform





Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.15	0.000	0.006
A2	2.20	2.50	0.087	0.098
A3	0.:	25	0.0	10
b	0.55	0.75	0.022	0.030
b1	5.00	5.30	0.197	0.209
b2	5.0	00	0.1	97
b3	0.	75	0.0	30
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.30	6.70	0.248	0.264
E	5.40	5.80	0.213	0.228
е	2.3	30	0.091	
HE	9.00	10.00	0.354	0.394
L	2.20	2.80	0.087	0.110
L1	0.80	1.40	0.031	0.055
L2	1.20	1.80	0.047	0.071
L3	5.30		0.209	
L4	0.9	90	0.0	35
Lp	1.00	1.60	0.039	0.063
X	_	0.25	_	0.010

DIM MILIME		MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
b5	_	1.00	-	0.04
b6	_	5.20	_	0.205
11	_	2.50	_	0.098
12	_	5.50	_	0.217
13	_	10.00	_	0.394

Dimension in mm / inches

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CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [f] Sealing or coating our Products with resin or other coating materials
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  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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